



**ELECTRONIC MATERIALS  
CMP TECHNOLOGIES**

**ACESOL® - series  
Colloidal Silica  
CMP Slurry**

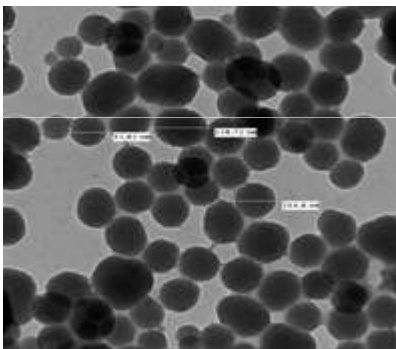
**ACE NANO CHEM**

# ACESOL® WP2010 (Wafer Edge Polishing Slurry)

## DESCRIPTION

Acesol® slurries offer a complete solution for your polishing requirements based on the latest colloidal silica technology showing exceptional stability and high manufacturing reproducibility

### TEM Image



Precisely Controlled  
ACESOL® Particles.

## KEY FEATURES

- Non-agglomerating slurries with tight Particle distributions
- Enables high removal rates
- Low solid contents, excellent uniformity, no defect
- Products development for customized applications
- Individual, non-setting spherical particles

## SPECIFICATION

Abrasive	Colloidal Silica
Mean Particle	80 -100 nm
Specific Gravity (20℃) g/cc	1.120
Solid Content (wt%)	20
Viscosity (25℃)	<5
pH (20℃)	11.40
Shelf life	1 Year

## Edge Roughness

	WP2010	Competitor
Apex	2.02 Å	2.08 Å
Front bevel	0.38 Å	0.33 Å
Back bevel	2.87 Å	3.52 Å

## Tool set-up

**Polisher : Fine Surface E-300 Type -- I ,II**

**Mixing rate : 19 : 1(DI water : Slurry)**

**Wafer Size : 12" Wafer**

**Analysis Method : Front & Back, Edge roughness(MP-2200)**